

PROCESS FOR MANUFACTURING A WIRING BOARD

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ABSTRACT OF THE DISCLOSURE

10 A resin plate having wiring pattern recesses and via
through holes is made. All of the surfaces of the resin
plate including inner walls of said wiring pattern
15 recesses and via through holes are coated with a metal
film. An electro-plating is applied using the metal film
as a power-supply layer to fill a plated metal into the
wiring pattern recesses and via through holes. The metal
film formed on the resin plate except for the inner walls
of the wiring pattern recesses and via through holes is
removed, so that wiring pattern and via are exposed on a
surface the same as that of the resin plate.